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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	8064
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	336
Number of Gates	500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax500-fg676m

Axcelerator Family Device Status

Axcelerator® Devices	Status
AX125	Production
AX250	Production
AX500	Production
AX1000	Production
AX2000	Production

Temperature Grade Offerings

Package	AX125	AX250	AX500	AX1000	AX2000
PQ208	–	C, I, M	C, I, M	–	–
CQ208	–	M	M	–	–
CQ256	–	–	–	–	M
FG256	C, I	C, I, M	–	–	–
FG324	C, I	–	–	–	–
CQ352	–	M	M	M	M
FG484	–	C, I, M	C, I, M	C, I, M	–
CG624	–	–	–	M	M
FG676	–	–	C, I, M	C, I, M	–
BG729	–	–	–	C, I, M	–
FG896	–	–	–	C, I, M	C, I, M
FG1152	–	–	–	–	C, I, M

C = Commercial
I = Industrial
M = Military

Speed Grade and Temperature Grade Matrix

Temperature Grade	Std	–1	–2
C	✓	✓	✓
I	✓	✓	✓
M	✓	✓	–

C = Commercial
I = Industrial
M = Military

Packaging Data

Refer to the following documents located on the Microsemi SoC Products Group website for additional packaging information.

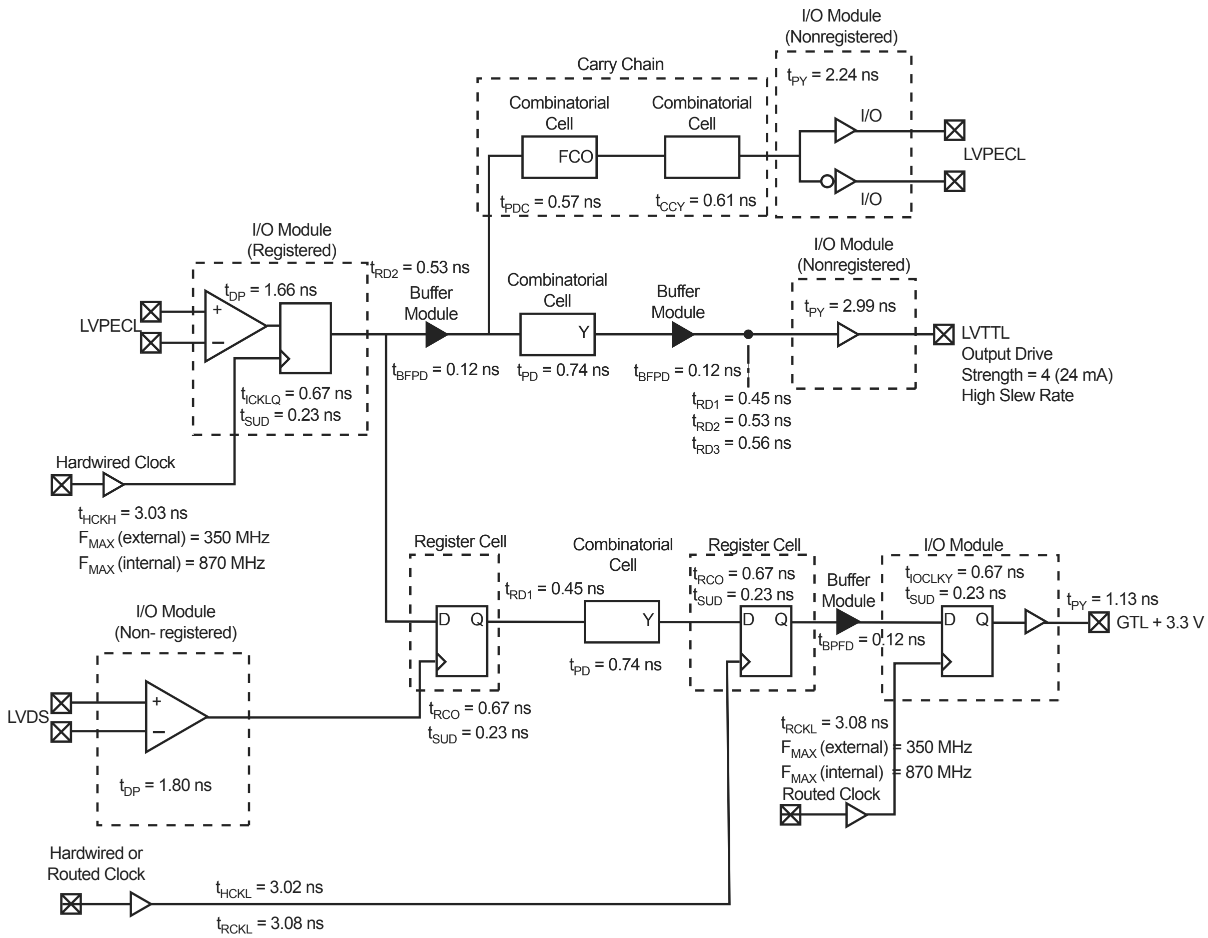
Package Mechanical Drawings

Package Thermal Characteristics and Weights

Hermatic Package Mechanical Information

Contact your local Microsemi representative for device availability.

Timing Model



Note: Worst case timing data for the AX1000, –2 speed grade

Figure 2-1 • **Worst Case Timing Data**

Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{HCKL}$

= (1.72 + 0.53 + 0.23) – 3.02 = –0.54 ns

Clock-to-Out (Pad-to-Pad)

$= t_{HCKL} + t_{RCO} + t_{RD1} + t_{PY}$

= 3.02 + 0.67 + 0.45 + 2.99 = 7.13 ns

Routed Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{RCKH}$

= (1.72 + 0.53 + 0.23) – 3.13 = –0.65 ns

Clock-to-Out (Pad-to-Pad)

$= t_{RCKH} + t_{RCO} + t_{RD1} + t_{PY}$

= 3.13 + 0.67 + 0.45 + 3.03 = 7.24 ns

Table 2-15, Table 2-16, and Table 2-17 list all the available macro names differentiated by I/O standard, type, slew rate, and drive strength.

***Table 2-15* • Macros for Single-Ended I/O Standards**

Standard	VCCI	Macro Names
LVTTL	3.3 V	CLKBUF, HCLKBUF INBUF, OUTBUF, OUTBUF_S_8, OUTBUF_S_12, OUTBUF_S_16, OUTBUF_S_24, OUTBUF_H_8, OUTBUF_H_12, OUTBUF_H_16, OUTBUF_H_24, TRIBUF, TRIBUF_S_8, TRIBUF_S_12, TRIBUF_S_16, TRIBUF_S_24, TRIBUF_H_8, TRIBUF_H_12, TRIBUF_H_16, TRIBUF_H_24, BIBUF, BIBUF_S_8, BIBUF_S_12, BIBUF_S_16, BIBUF_S_24, BIBUF_H_8, BIBUF_H_12, BIBUF_H_16, BIBUF_H_24
3.3 V PCI	3.3 V	CLKBUF_PCI, HCLKBUF_PCI, INBUF_PCI, OUTBUF_PCI, TRIBUF_PCI, BIBUF_PCI
3.3 V PCI-X	3.3 V	CLKBUF_PCI-X, HCLKBUF_PCI-X, INBUF_PCI-X, OUTBUF_PCI-X, TRIBUF_PCI-X, BIBUF_PCI-X
LVCMOS25	2.5 V	CLKBUF_LVCMOS25, HCLKBUF_LVCMOS25, INBUF_LVCMOS25, OUTBUF_LVCMOS25, TRIBUF_LVCMOS25, BIBUF_LVCMOS25
LVCMOS18	1.8 V	CLKBUF_LVCMOS18, HCLKBUF_LVCMOS18, INBUF_LVCMOS18, OUTBUF_LVCMOS18, TRIBUF_LVCMOS18, BIBUF_LVCMOS18
LVCMOS15 (JESD8-11)	1.5 V	CLKBUF_LVCMOS15, HCLKBUF_LVCMOS15, INBUF_LVCMOS15, OUTBUF_LVCMOS15, TRIBUF_LVCMOS15, BIBUF_LVCMOS15

***Table 2-16* • I/O Macros for Differential I/O Standards**

Standard	VCCI	Macro Names
LVPECL	3.3 V	CLKBUF_LVPECL, HCLKBUF_LVPECL, INBUF_LVPECL, OUTBUF_LVPECL
LVDS	2.5 V	CLKBUF_LVDS, HCLKBUF_LVDS, INBUF_LVDS, OUTBUF_LVDS

***Table 2-17* • I/O Macros for Voltage-Referenced I/O Standards**

Standard	VCCI	VREF	Macro Names
GTL+	3.3 V	1.0 V	CLKBUF_GTP33, HCLKBUF_GTP33, INBUF_GTP33, OUTBUF_GTP33, TRIBUF_GTP33, BIBUF_GTP33
GTL+	2.5 V	1.0 V	CLKBUF_GTP25, HCLKBUF_GTP25, INBUF_GTP25, OUTBUF_GTP25, TRIBUF_GTP25, BIBUF_GTP25
SSTL2 Class I	2.5 V	1.25 V	CLKBUF_SSTL2_I, HCLKBUF_SSTL2_I, INBUF_SSTL2_I, OUTBUF_SSTL2_I, TRIBUF_SSTL2_I, BIBUF_SSTL2_I
SSTL2 Class II	2.5 V	1.25 V	CLKBUF_SSTL2_II, HCLKBUF_SSTL2_II, INBUF_SSTL2_II, OUTBUF_SSTL2_II, TRIBUF_SSTL2_II, BIBUF_SSTL2_II
SSTL3 Class I	3.3 V	1.5 V	CLKBUF_SSTL3_I, HCLKBUF_SSTL3_I, INBUF_SSTL3_I, OUTBUF_SSTL3_I, TRIBUF_SSTL3_I, BIBUF_SSTL3_I
SSTL3 Class II	3.3 V	1.5 V	CLKBUF_SSTL3_II, HCLKBUF_SSTL3_II, INBUF_SSTL3_II, OUTBUF_SSTL3_II, TRIBUF_SSTL3_II, BIBUF_SSTL3_II
HSTL Class I	1.5 V	0.75 V	CLKBUF_HSTL_I, HCLKBUF_HSTL_I, INBUF_HSTL_I, OUTBUF_HSTL_I, TRIBUF_HSTL_I, BIBUF_HSTL_I

3.3 V LVTTL

Low-Voltage Transistor-Transistor Logic is a general purpose standard (EIA/JESD) for 3.3 V applications. It uses an LVTTL input buffer and push-pull output buffer.

***Table 2-20* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
–0.3	0.8	2.0	3.6	0.4	2.4	24	–24

AC Loadings

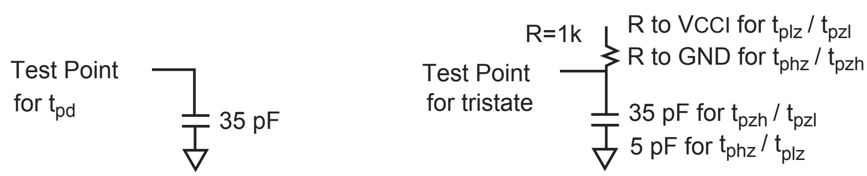


***Figure 2-15* • AC Test Loads**

***Table 2-21* • AC Waveforms, Measuring Points, and Capacitive Load**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
0	3.0	1.40	N/A	35

*Note: * Measuring Point = VTRIP*

1.5 V LVCMOS (JESD8-11)

Low-Voltage Complementary Metal-Oxide Semiconductor for 1.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.5 V applications. It uses a 3.3 V tolerant CMOS input buffer and a push-pull output buffer.

Table 2-29 **• DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
–0.3	0.35 VCCI	0.65 VCCI	3.6	0.4	VCCI – 0.4	8 mA	–8 mA

AC Loadings

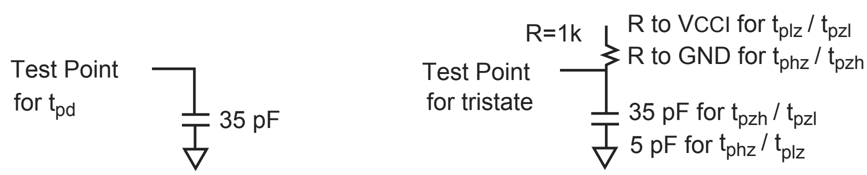


Table 2-30 **• AC Test Loads**

Table 2-31 **• AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
0	1.5	$0.5V_{CCI}$	N/A	35

*Note: * Measuring Point = VTRIP*

***Table 2-57* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)
1.2 – 0.125	1.2 + 0.125	1.2

*Note: * Measuring Point = VTRIP*

Timing Characteristics

***Table 2-58* • LVDS I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVDS Output Module Timing								
t_{DP}	Input Buffer		1.80		2.05		2.41	ns
t_{PY}	Output Buffer		2.32		2.64		3.11	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Global Resources

One of the most important aspects of any FPGA architecture is its global resources or clocks. The Axcelerator family provides the user with flexible and easy-to-use global resources, without the limitations normally found in other FPGA architectures.

The AX architecture contains two types of global resources, the HCLK (hardwired clock) and CLK (routed clock). Every Axcelerator device is provided with four HCLKs and four CLKs for a total of eight clocks, regardless of device density.

Hardwired Clocks

The hardwired (HCLK) is a low-skew network that can directly drive the clock inputs of all sequential modules (R-cells, I/O registers, and embedded RAM/FIFOs) in the device with no antifuse in the path. All four HCLKs are available everywhere on the chip.

Timing Characteristics

Table 2-70 **• AX125 Dedicated (Hardwired) Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Dedicated (Hardwired) Array Clock Networks								
t_{HCKL}	Input Low to High		3.02		3.44		4.05	ns
t_{HCKH}	Input High to Low		3.03		3.46		4.06	ns
t_{HPWH}	Minimum Pulse Width High	0.58		0.65		0.77		ns
t_{HPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{HCKSW}	Maximum Skew		0.06		0.07		0.08	ns
t_{HP}	Minimum Period	1.15		1.31		1.54		ns
t_{HMAX}	Maximum Frequency		870		763		649	MHz

Table 2-71 **• AX250 Dedicated (Hardwired) Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Dedicated (Hardwired) Array Clock Networks								
t_{HCKL}	Input Low to High		2.57		2.93		3.45	ns
t_{HCKH}	Input High to Low		2.61		2.97		3.50	ns
t_{HPWH}	Minimum Pulse Width High	0.58		0.65		0.77		ns
t_{HPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{HCKSW}	Maximum Skew		0.06		0.07		0.08	ns
t_{HP}	Minimum Period	1.15		1.31		1.54		ns
t_{HMAX}	Maximum Frequency		870		763		649	MHz

PLL Configurations

The following rules apply to the different PLL inputs and outputs:

Reference Clock

The RefCLK can be driven by (Figure 2-50):

1. Global routed clocks (CLKE/F/G/H) or user-created clock network
2. CLK1 output of an adjacent PLL
3. [H]CLKxP (single-ended or voltage-referenced)
4. [H]CLKxP/[H]CLKxN pair (differential modes like LVPECL or LVDS)

Feedback Clock

The feedback clock can be driven by (Figure 2-51 on page 2-78):

1. Global routed clocks (CLKE/F/G/H) or user-created clock network
2. External [H]CLKxP/N I/O pad(s) from the adjacent PLL cell
3. An internal signal from the PLL block

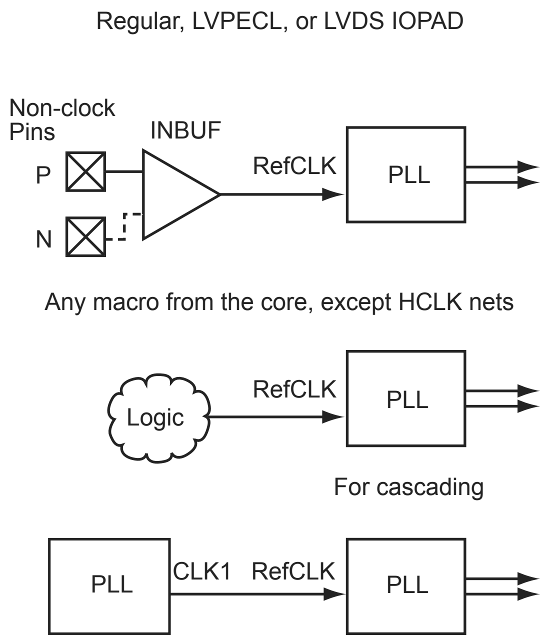


Figure 2-50 **• Reference Clock Connections**

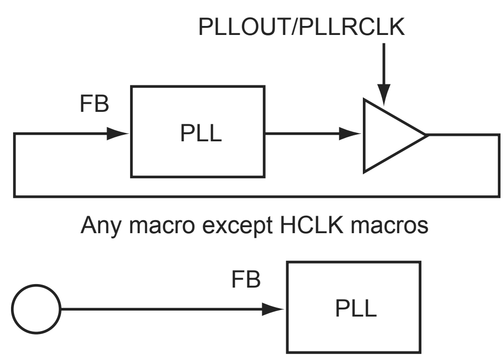


Figure 2-51 **• Feedback Clock Connections**

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

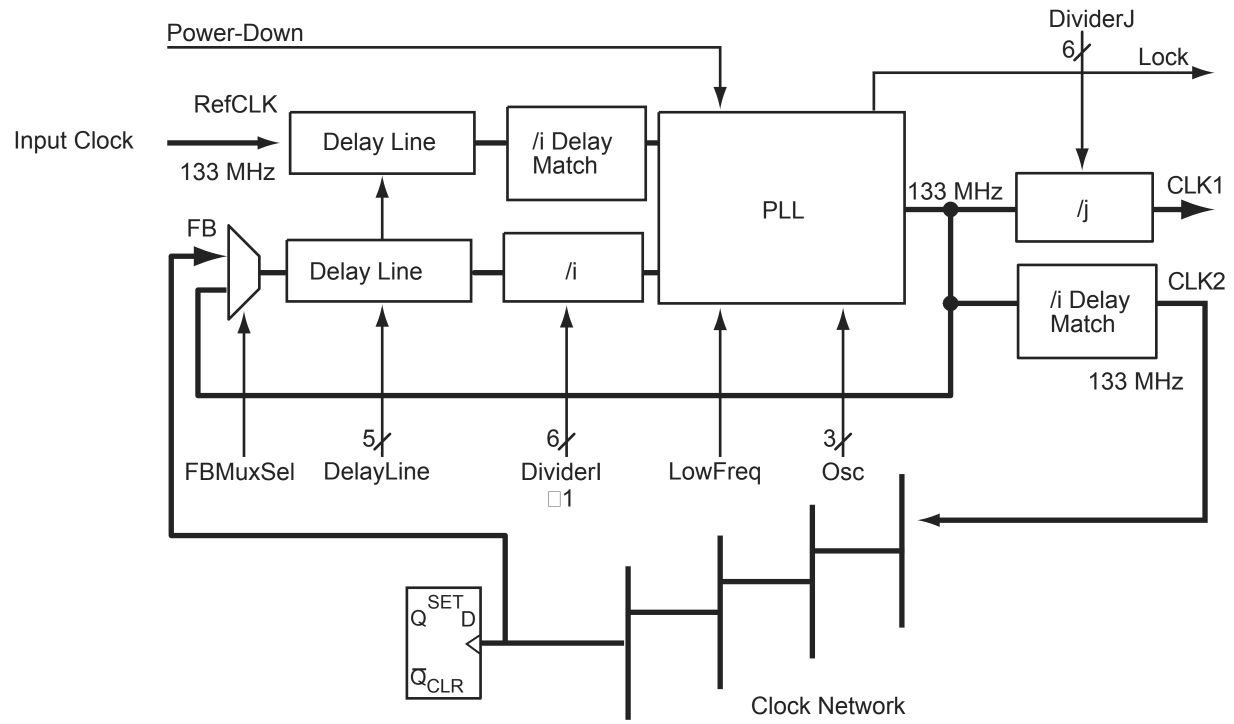


Figure 2-56 • **Using the PLL for Clock Deskewing**

RAM

Each memory block consists of 4,608 bits that can be organized as 128x36, 256x18, 512x9, 1kx4, 2kx2, or 4kx1 and are cascadable to create larger memory sizes. This allows built-in bus width conversion (Table 2-86). Each block has independent read and write ports which enable simultaneous read and write operations.

Table 2-86 **• Memory Block WxD Options**

Data-word (in bits)	Depth	Address Bus	Data Bus
1	4,096	RA/WA[11:0]	RD/WD[0]
2	2,048	RA/WA[10:0]	RD/WD[1:0]
4	1,024	RA/WA[9:0]	RD/WD[3:0]
9	512	RA/WA[8:0]	RD/WD[8:0]
18	256	RA/WA[7:0]	RD/WD[17:0]
36	128	RA/WA[6:0]	RD/WD[35:0]

Clocks

The RCLK and the WCLK have independent source polarity selection and can be sourced by any global or local signal.

RAM Configurations

The AX architecture allows the read side and write side of RAMs to be organized independently, allowing for bus conversion. For example, the write side can be set to 256x18 and the read side to 512x9.

Both the write width and read width for the RAM blocks can be specified independently and changed dynamically with the WW (write width) and RW (read width) pins. The D x W different configurations are: 128 x 36, 256 x 18, 512 x 9, 1k x 4, 2k x 2, and 4k x 1. The allowable RW and WW values are shown in Table 2-87.

Table 2-87 **• Allowable RW and WW Values**

RW(2:0)	WW(2:0)	D x W
000	000	4k x 1
001	001	2k x 2
010	010	1k x 4
011	011	512 x 9
100	100	256 x 18
101	101	128 x 36
11x	11x	reserved

When widths of one, two, and four are selected, the ninth bit is unused. For example, when writing nine-bit values and reading four-bit values, only the first four bits and the second four bits of each nine-bit value are addressable for read operations. The ninth bit is not accessible. Conversely, when writing four-bit values and reading nine-bit values, the ninth bit of a read operation will be undefined.

Table 2-101 **• Eight FIFO Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		15.46		17.61		20.70	ns
t_{WHD}	Write Hold		0.00		0.00		0.00	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		5.13		5.13		5.13	ns
t_{WCKP}	Minimum WCLK Period	5.88		5.88		5.88		ns
t_{RSU}	Read Setup		16.22		18.47		21.72	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.73		0.73		0.73	ns
t_{RCKL}	RCLK Low		5.77		5.77		5.77	ns
t_{RCKP}	Minimum RCLK period	6.50		6.50		6.50		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		3.39		3.86		4.54	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Nonpipelined)		4.93		5.62		6.61	ns

Note: Timing data for these eight cascaded FIFO blocks uses a depth of 32,768. For all other combinations, use Microsemi's timing software.

Table 2-102 • Sixteen FIFO Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		16.32		18.60		21.86	ns
t_{WHD}	Write Hold		0.00		0.00		0.00	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		13.40		13.40		13.40	ns
t_{WCKP}	Minimum WCLK Period	14.15		14.15		14.15		ns
t_{RSU}	Read Setup		17.16		19.54		22.97	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.73		0.73		0.73	ns
t_{RCKL}	RCLK Low		14.41		14.41		14.41	ns
t_{RCKP}	Minimum RCLK period	15.14		15.14		15.14		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		12.08		13.76		16.17	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Nonpipelined)		12.83		14.62		17.18	ns

Note: *Timing data for these sixteen cascaded FIFO blocks uses a depth of 65,536. For all other combinations, use Microsemi's timing software.*

Building RAM and FIFO Modules

RAM and FIFO modules can be generated and included in a design in two different ways:

- Using the SmartGen Core Generator where the user defines the depth and width of the FIFO/RAM, and then instantiates this block into the design (refer to the *SmartGen, FlashROM, Analog System Builder, and Flash Memory System Builder* User's Guide for more information).
- The alternative is to instantiate the RAM/FIFO blocks manually, using inverters for polarity control and tying all unused data bits to ground.

Other Architectural Features

Low Power Mode

Although designed for high performance, the AX architecture also allows the user to place the device into a low power mode. Each I/O bank in an Axcelerator device can be configured individually, when in low power mode, to tristate all outputs, disable inputs, or both. The low power mode is activated by asserting the LP pin, which is grounded in normal operation.

While in the low power mode, the device is still fully functional and all internal logic states are preserved. This allows a user to disable all but a few signals and operate the part in a low-frequency, watchdog throughout the fabric of the device and may be programmed by the user to thwart attempts to reverse engineer the device by attempting to exploit either the programming or probing interfaces. Both invasive and noninvasive attacks against an Axcelerator device that access or bypass these security fuses will destroy access to the rest of the device. (refer to the *Design Security in Nonvolatile Flash and Antifuse FPGAs* white paper).

Look for this symbol to ensure your valuable IP is protected with highest level of security in the industry.

Figure 2-69 • **FuseLock Logo**

To ensure maximum security in Axcelerator devices, it is recommended that the user program the device security fuse (SFUS). When programmed, the Silicon Explorer II testing probes are disabled to prevent internal probing, and the programming interface is also disabled. All JTAG public instructions are still accessible by the user.

For more information, refer to the *Implementation of Security in Actel Antifuse FPGAs* application note.

Global Set Fuse

The Global Set Fuse determines if all R-cells and I/O registers (InReg, OutReg, and EnReg) are either cleared or preset by driving the GCLR and GPSET inputs of all R-cells and I/O Registers (Figure 2-31 on page 2-58). Default setting is to clear all registers (GCLR = 0 and GPSET =1) at device power-up. When the GBSETFUS option is checked during FUSE file generation, all registers are preset (GCLR = 1 and GPSET= 0). A local CLR or PRESET will take precedence over this setting. Both pins are pulled High during normal device operation. For use details, see the Libero IDE online help.

Silicon Explorer II Probe Interface

Silicon Explorer II is an integrated hardware and software solution that, in conjunction with the Designer tools, allows users to examine any of the internal nets (except I/O registers) of the device while it is operating in a prototype or a production system. The user can probe up to four nodes at a time without changing the placement and routing of the design and without using any additional device resources. Highlighted nets in Designer's ChipPlanner can be accessed using Silicon Explorer II in order to observe their real time values.

Silicon Explorer II's noninvasive method does not alter timing or loading effects, thus shortening the debug cycle. In addition, Silicon Explorer II does not require relayout or additional MUXes to bring signals out to external pins, which is necessary when using programmable logic devices from other suppliers. By eliminating multiple place-and-route program cycles, the integrity of the design is maintained throughout the debug process.

Each member of the Axcelerator family has four external pads: PRA, PRB, PRC, and PRD. These can be used to bring out four probe signals from the Axcelerator device (note that the AX125 only has two probe signals that can be observed: PRA and PRB). Each core tile has up to two probe signals. To disallow probing, the SFUS security fuse in the silicon signature has to be programmed (see "Special Fuses" on page 2-108).

Silicon Explorer II connects to the host PC using a standard serial port connector. Connections to the circuit board are achieved using a nine-pin D-Sub connector (Figure 1-9 on page 1-7). Once the design has been placed-and-routed, and the Axcelerator device has been programmed, Silicon Explorer II can be connected and the Explorer software can be launched.

Silicon Explorer II comes with an additional optional PC hosted tool that emulates an 18-channel logic analyzer. Four channels are used to monitor four internal nodes, and 14 channels are available to probe external signals. The software included with the tool provides the user with an intuitive interface that allows for easy viewing and editing of signal waveforms.

FG676	
AX500 Function	Pin Number
GND	R10
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A11
NC	A21

FG676	
AX500 Function	Pin Number
NC	A22
NC	A24
NC	A25
NC	AA11
NC	AA19
NC	AA20
NC	AA4
NC	AA5
NC	AA6
NC	AA7
NC	AA8
NC	AA9
NC	AB1
NC	AB11
NC	AB17
NC	AB18
NC	AB19
NC	AB20
NC	AB8
NC	AB9
NC	AC1
NC	AC13
NC	AC14
NC	AC25
NC	AD1
NC	AD11
NC	AD16
NC	AD25
NC	AE1
NC	AF2
NC	AF25
NC	B11
NC	B24
NC	B4
NC	C16

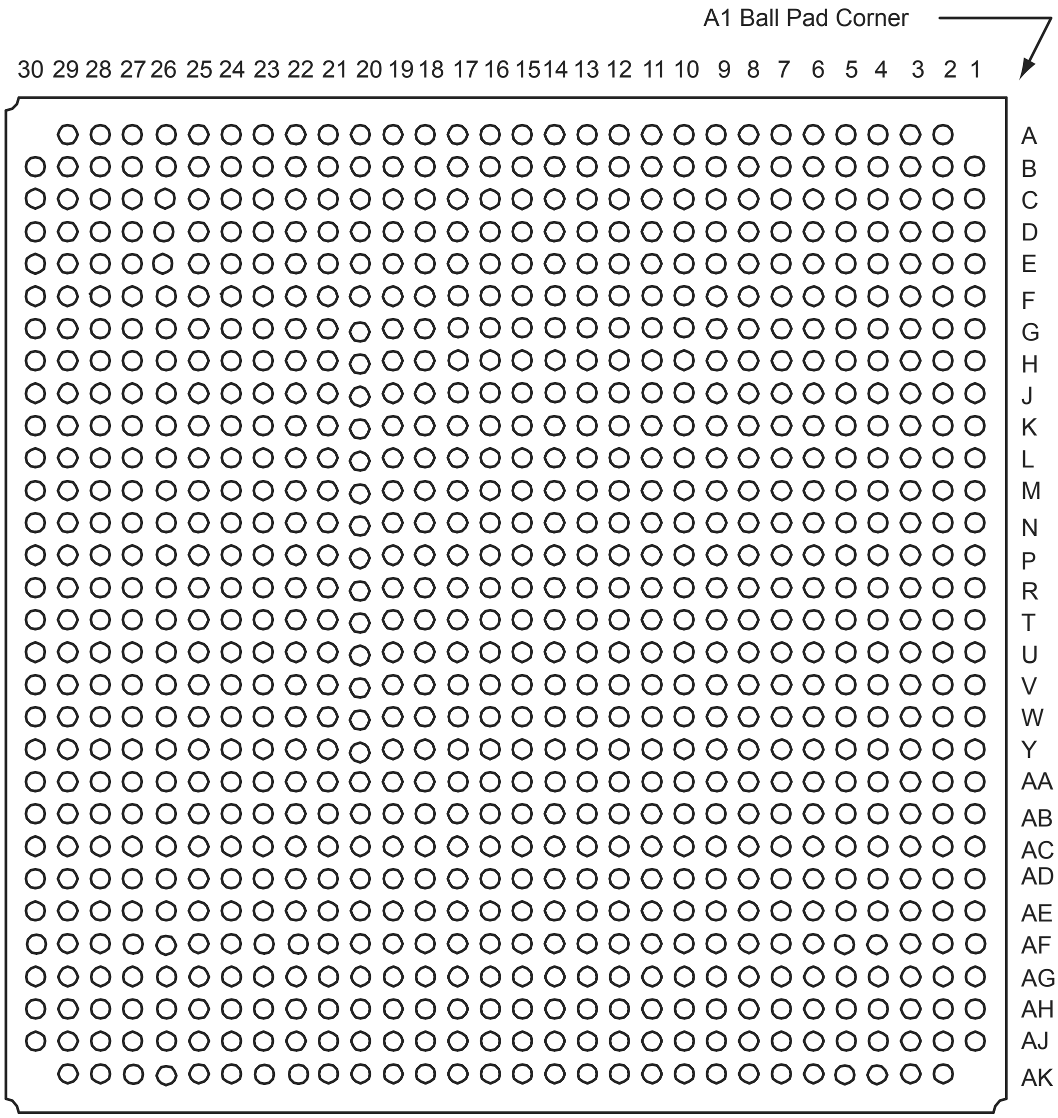
FG676	
AX500 Function	Pin Number
NC	C4
NC	D1
NC	D13
NC	D14
NC	D17
NC	D18
NC	D2
NC	D26
NC	D3
NC	D9
NC	E1
NC	E18
NC	E23
NC	E24
NC	E26
NC	E3
NC	E4
NC	E9
NC	F1
NC	F18
NC	F20
NC	F21
NC	F22
NC	F23
NC	F24
NC	F4
NC	F6
NC	F7
NC	G21
NC	G22
NC	H21
NC	H22
NC	H23
NC	H5
NC	H6

FG676	
AX1000 Function	**Pin Number**
IO129PB4F12	AA21
IO131NB4F12	AD22
IO131PB4F12	AD23
IO132NB4F12	AE23
IO132PB4F12	AE24
IO133NB4F12	AB20
IO133PB4F12	AA20
IO134NB4F12	AC21
IO134PB4F12	AC22
IO135NB4F12	AF22
IO135PB4F12	AF23
IO137NB4F12	AB19
IO137PB4F12	AA19
IO139NB4F13	AC19
IO139PB4F13	AC20
IO140NB4F13	AE21
IO140PB4F13	AE22
IO141NB4F13	AD20
IO141PB4F13	AD21
IO143NB4F13	AB17
IO143PB4F13	AB18
IO144NB4F13	AE19
IO144PB4F13	AE20
IO145NB4F13	AC17
IO145PB4F13	AC18
IO146NB4F13	AD18
IO146PB4F13	AD19
IO147NB4F13	AA17
IO147PB4F13	AA18
IO148NB4F13	AF20
IO148PB4F13	AF21
IO149NB4F13	AA16
IO149PB4F13	Y16
IO151NB4F13	AC16
IO151PB4F13	AB16
IO153NB4F14	AE17

FG676	
AX1000 Function	**Pin Number**
IO153PB4F14	AE18
IO154NB4F14	AF17
IO154PB4F14	AF18
IO155NB4F14	AA15
IO155PB4F14	Y15
IO157NB4F14	AC15
IO157PB4F14	AB15
IO159NB4F14/CLKEN	AE16
IO159PB4F14/CLKEP	AF16
IO160NB4F14/CLKFN	AE14
IO160PB4F14/CLKFP	AE15
Bank 5	
IO161NB5F15/CLKGN	AE12
IO161PB5F15/CLKGP	AE13
IO162NB5F15/CLKHN	AE11
IO162PB5F15/CLKHP	AF11
IO163NB5F15	AC12
IO163PB5F15	AB12
IO165NB5F15	Y12
IO165PB5F15	AA13
IO167NB5F15	Y11
IO167PB5F15	AA12
IO168NB5F15	AF9
IO168PB5F15	AF10
IO169NB5F15	AB11
IO169PB5F15	AA11
IO171NB5F16	AE9
IO171PB5F16	AE10
IO173NB5F16	AC10
IO173PB5F16	AC11
IO174NB5F16	AE7
IO174PB5F16	AE8
IO175NB5F16	AC9
IO175PB5F16	AD9
IO176NB5F16	AF6
IO176PB5F16	AF7

FG676	
AX1000 Function	**Pin Number**
IO177NB5F16	AA10
IO177PB5F16	AB10
IO179NB5F16	AD7
IO179PB5F16	AD8
IO180NB5F16	AC7
IO180PB5F16	AC8
IO181NB5F17	AA9
IO181PB5F17	AB9
IO183NB5F17	AD6
IO183PB5F17	AE6
IO184NB5F17	AE5
IO184PB5F17	AF5
IO185NB5F17	AA8
IO185PB5F17	AB8
IO187NB5F17	AC5
IO187PB5F17	AC6
IO188NB5F17	AD4
IO188PB5F17	AD5
IO189NB5F17	AB6
IO189PB5F17	AB7
IO190NB5F17	AF4
IO190PB5F17	AE4
IO191NB5F17	AE3
IO191PB5F17	AF3
IO192NB5F17	AA6
IO192PB5F17	AA7
Bank 6	
IO193NB6F18	Y5
IO193PB6F18	AA5
IO194NB6F18	AB3
IO194PB6F18	AC3
IO195NB6F18	Y4
IO195PB6F18	AA4
IO196NB6F18	AC2
IO196PB6F18	AD2
IO197NB6F18	W6

FG896



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896	
AX1000 Function	**Pin Number**
GND	A13
GND	A18
GND	A2
GND	A23
GND	A29
GND	A8
GND	AA10
GND	AA21
GND	AA28
GND	AA3
GND	AB2
GND	AB22
GND	AB29
GND	AB9
GND	AC1
GND	AC30
GND	AE25
GND	AE6
GND	AF26
GND	AF5
GND	AG27
GND	AG4
GND	AH10
GND	AH15
GND	AH16
GND	AH21
GND	AH28
GND	AH3
GND	AJ1
GND	AJ2
GND	AJ22
GND	AJ29
GND	AJ30
GND	AJ9
GND	AK13

FG896	
AX1000 Function	**Pin Number**
GND	AK18
GND	AK2
GND	AK23
GND	AK29
GND	AK8
GND	B1
GND	B2
GND	B22
GND	B29
GND	B30
GND	B9
GND	C10
GND	C15
GND	C16
GND	C21
GND	C28
GND	C3
GND	D27
GND	D28
GND	D4
GND	E26
GND	E5
GND	H1
GND	H30
GND	J2
GND	J22
GND	J29
GND	J9
GND	K10
GND	K21
GND	K28
GND	K3
GND	L11
GND	L20
GND	M12

FG896	
AX1000 Function	**Pin Number**
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	M18
GND	M19
GND	N1
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N18
GND	N19
GND	N30
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P18
GND	P19
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	R18
GND	R19
GND	R28
GND	R3

CG624	
AX2000 Function	Pin Number
IO75PB1F6	D17
IO76NB1F7	C21
IO76PB1F7	C20
IO79NB1F7	H20
IO79PB1F7	H19
IO80NB1F7	E18
IO80PB1F7	F18
IO81NB1F7	G21
IO81PB1F7	G20
IO82NB1F7	F20
IO82PB1F7	F19
IO85NB1F7	D20*
IO85PB1F7	D19*
Bank 2	
IO86NB2F8	F23
IO86PB2F8	E23
IO87NB2F8	H23
IO87PB2F8	G23
IO88NB2F8	E24
IO88PB2F8	D24
IO89NB2F8	M17*
IO89PB2F8	G22*
IO91NB2F8	J22
IO91PB2F8	H22
IO92NB2F8	L18
IO92PB2F8	K18
IO96NB2F9	G24
IO96PB2F9	F24
IO97NB2F9	J21
IO97PB2F9	J20
IO98PB2F9	J23
IO99NB2F9	L19

Note: **Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	Pin Number
IO99PB2F9	K19
IO100NB2F9	E25
IO100PB2F9	D25
IO103PB2F9	K20
IO105NB2F9	M19
IO105PB2F9	M18
IO106NB2F9	J24
IO106PB2F9	H24
IO107NB2F10	L23*
IO107PB2F10	N16*
IO109NB2F10	L22
IO109PB2F10	K22
IO110NB2F10	G25
IO110PB2F10	F25
IO111NB2F10	L21
IO111PB2F10	L20
IO112NB2F10	L24
IO112PB2F10	K24
IO113NB2F10	N17
IO115NB2F10	M20
IO115PB2F10	M21
IO117NB2F10	N19
IO117PB2F10	N18
IO118NB2F11	J25
IO121NB2F11	N24
IO121PB2F11	M24
IO122NB2F11	L25
IO122PB2F11	K25
IO123NB2F11	N22
IO123PB2F11	M22
IO124NB2F11	N23
IO124PB2F11	M23

Note: **Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	Pin Number
IO127NB2F11	P18
IO127PB2F11	P17
IO128NB2F11	N25
IO128PB2F11	M25
Bank 3	
IO129NB3F12	N20
IO130PB3F12	P24
IO131NB3F12	P21
IO133NB3F12	P20
IO133PB3F12	P19
IO138NB3F12	R23
IO138PB3F12	P23
IO139NB3F13	R22
IO139PB3F13	P22
IO141NB3F13	R19
IO142NB3F13	R25
IO142PB3F13	P25
IO143PB3F13	R21
IO145NB3F13	T18
IO145PB3F13	R18
IO146NB3F13	T24
IO146PB3F13	R24
IO147NB3F13	T20
IO147PB3F13	R20
IO148NB3F13	U25
IO148PB3F13	T25
IO149NB3F13	T22
IO153NB3F14	U19
IO153PB3F14	T19
IO154NB3F14	Y25
IO154PB3F14	W25
IO157NB3F14	V20

Note: **Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

Revision	Changes	Page
Revision 10 (continued)	The "TRST" section was updated.	2-107
	The "Global Set Fuse" section was added.	2-109
	A footnote was added to "FG896" for the AX2000 regarding pins AB1, AE2, G1, and K2.	3-52
	Pinouts for the AX250, AX500, and AX1000 were added for "CQ352".	3-98
	Pinout for the AX1000 was added for "CG624".	3-115
Revision 9 (v2.1)	Table 2-79 was updated.	2-69
	The "Low Power Mode" section was updated.	2-106
Revision 8 (v2.0)	Table 1 has been updated.	i
	The "Ordering Information" section has been updated.	ii
	The "Device Resources" section has been updated.	ii
	The "Temperature Grade Offerings" section is new.	iii
	The "Speed Grade and Temperature Grade Matrix" section has been updated.	iii
	Table 2-9 has been updated.	2-12
	Table 2-10 has been updated.	2-12
	Table 2-1 has been updated.	2-1
	Table 2-2 has been updated.	2-1
	Table 2-3 has been updated.	2-2
	Table 2-4 has been updated.	2-3
	Table 2-5 has been updated.	2-4
	The "Power Estimation Example" section has been updated.	2-5
	The "Thermal Characteristics" section has been updated.	2-6
	The "Package Thermal Characteristics" section has been updated.	2-6
	The "Timing Characteristics" section has been updated.	2-7
	The "Pin Descriptions" section has been updated.	2-9
	Timing numbers have been updated from the "3.3 V LVTTL" section to the "Timing Characteristics" section. Many AC Loads were updated as well.	2-25 to 2-59
	Timing characteristics for the "Hardwired Clocks" and "Routed Clocks" sections were updated.	2-66, 2-68
	Table 2-89 to Table 2-92 and Table 2-98 to Table 2-99 were updated.	2-90 to 2-93, 2-102 to 2-103
	The following sections were updated: "Low Power Mode", "Interface", "Data Registers (DRs)", "Security", "Silicon Explorer II Probe Interface", and "Programming"	2-106 to 2-110
	In the "PQ208" (AX500) section, pins 2, 52, and 156 changed from V_{CCDA} to V_{CCA}. For pins 170 and 171, the I/O names refer to pair 23 instead of 24.	3-84